INTEGRATED CIRCUITS

DATA SHEET

74LV03Quad 2-input NAND gate

Product data Supersedes data of 1998 Apr 20





Quad 2-input NAND gate

74LV03

FEATURES

- Wide operating voltage: 1.0 V to 5.5 V
- Optimized for Low Voltage applications: 1.0 V to 3.6 V
- Accepts TTL input levels between V_{CC} = 2.7 V and V_{CC} = 3.6 V
- Typical V_{OLP} (output ground bounce) < 0.8 V @ V_{CC} = 3.3 V, T_{amb} = 25 °C
- Typical V_{OHV} (output V_{OH} undershoot) > 2 V @ V_{CC} = 3.3 V, T_{amb} = 25 °C
- Level shifter capability
- Output capability: standard (open drain)
- I_{CC} category: SSI

DESCRIPTION

The 74LV03 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT03.

The 74LV03 provides the 2-input NAND function.

The 74LV03 has open-drain N-transistor outputs, which are not clamped by a diode connected to $V_{\mbox{\footnotesize{CC}}}.$ In the OFF-state, i.e., when one input is LOW, the output may be pulled to any voltage between GND and V_{Omax}. This allows the device to be used as a LOW-to-HIGH or HIGH-to-LOW level shifter. For digital operation and OR-tied output applications, these devices must have a pull-up resistor to establish a logic HIGH level.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25 \, ^{\circ}C$; $t_r = t_f \le 2.5 \, \text{ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PZL} /t _{PLZ}	Propagation delay nA, nB to nY	C _L = 15 pF V _{CC} = 3.3 V	8	ns
C _I Input capacitance			3.5	pF
C _{PD}	Power dissipation capacitance per gate	Notes 1, 2	4	pF

NOTES:

- C_{PD} is used to determine the dynamic power dissipation (P_D in μW)
 - $$\begin{split} &P_D = C_{PD} \times V_{CC}{}^2 \times f_i \times N + \Sigma \left(C_L \times V_{CC}{}^2 \times f_o \right) \quad \text{where:} \\ &N = \text{the number of outputs switching;} \end{split}$$

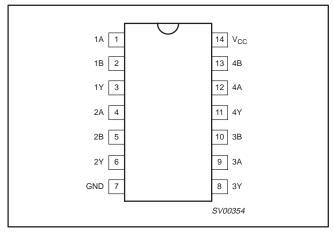
 - f_i = input frequency in MHz; C_L = output load capacitance in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V;

 - $\Sigma (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$ The condition is $V_1 = GND$ to V_{CC}
- The given value of C_{PD} is obtained with : $C_L = 0$ pF and $R_L = \infty$

ORDERING INFORMATION

PACKA	GES	TEMPERATURE RANGE	ORDER CODE	PKG. DWG. #
14-Pin Plastic SO		–40 °C to +125 °C	74LV03D	SOT108-1

PIN CONFIGURATION



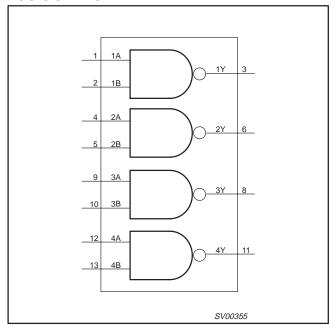
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1, 4, 9, 12	1A to 4A	Data inputs
2, 5, 10, 13	1B to 4B	Data inputs
3, 6, 8, 11	1Y to 4Y	Data outputs
7 GND		Ground (0 V)
14 V _{CC}		Positive supply voltage

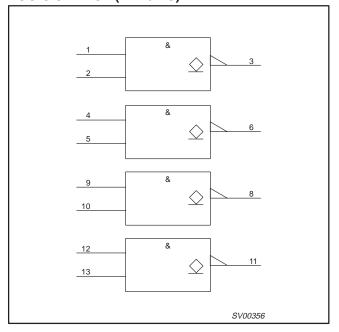
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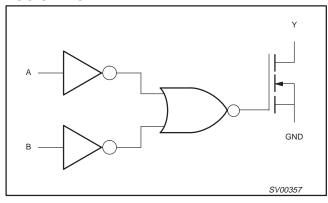
LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



LOGIC DIAGRAM



FUNCTION TABLE

INP	OUTPUT	
nA	nA nB	
L	L	Z
L	Н	Z
Н	L	Z
Н	Н	L

NOTES:
H = HIGH voltage level
L = LOW voltage level
Z = High impedance OFF-state

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CC}	DC supply voltage	See Note1	1.0	3.3	5.5	V
VI	Input voltage		0	_	V _{CC}	V
V _O	Output voltage		0	-	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
		$V_{CC} = 1.0 \text{ V to } 2.0 \text{ V}$	_	_	500	ns/V
	Input rise and fall times	$V_{CC} = 2.0 \text{ V to } 2.7 \text{ V}$	_	-	200	
t _r , t _f	input use and fail times	V _{CC} = 2.7 V to 3.6 V	_	_	100	
		$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$	_	-	50	

NOTES:

ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
±I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ or } V_{I} > V_{CC} + 0.5 \text{ V}$	20	mA
±I _{OK}	DC output diode current $V_O < -0.5 \text{ or } V_O > V_{CC} + 0.5 \text{ V}$		50	mA
±ΙΟ	DC output source or sink current – standard outputs	$-0.5V < V_O < V_{CC} + 0.5 V$	25	mA
±I _{GND} , ±I _{CC}	DC V _{CC} or GND current for types with –standard outputs		50	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package –plastic mini-pack (SO)	for temperature range: -40 °C to +125 °C above +70 °C derate linearly with 8 mW/K	500	mW

NOTES:

¹ The LV is guaranteed to function down to V_{CC} = 1.0 V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2 V to V_{CC} = 5.5 V.

¹ Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

² The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0 V)

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40	-40°C to +85°C -40°C to +1		o +125°C	UNIT	
			MIN	TYP ¹	MAX	MIN	MAX	1
		V _{CC} = 1.2 V	0.9			0.9		
VIH	HIGH level Input	V _{CC} = 2.0 V	1.4			1.4]
VIН	voltage	V _{CC} = 2.7 V to 3.6 V	2.0			2.0		1 °
		V _{CC} = 4.5 V to 5.5 V	0.7*V _{CC}			0.7*V _{CC}		1
		V _{CC} = 1.2 V			0.3		0.3	
V_{IL}	LOW level Input	V _{CC} = 2.0 V			0.6		0.6] _/
۷IL	voltage	V _{CC} = 2.7 V to 3.6 V			0.8		0.8	1 °
		V _{CC} = 4.5 V to 5.5 V			0.3*V _{CC}		0.3*V _{CC}	1
		$V_{CC} = 1.2 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu\text{A}$		1.2				
		$V_{CC} = 2.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu\text{A}$	1.8	2.0		1.8		1
V_{OH}	HIGH level output voltage; all outputs	$V_{CC} = 2.7 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu\text{A}$	2.5	2.7		2.5		
	Voltago, all outputo	$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu\text{A}$	2.8	3.0		2.8		1
		$V_{CC} = 4.5 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu\text{A}$	4.3	4.5		4.3		1
V _{OH}	HIGH level output voltage;	$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 6 \text{ mA}$	2.40	2.82		2.20		V
VОН	STANDARD outputs	$V_{CC} = 4.5 \text{ V;} V_{I} = V_{IH} \text{ or } V_{IL;} -I_{O} = 12 \text{ mA}$	3.60	4.20		3.50] `
		$V_{CC} = 1.2 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}, I_O = 100 \mu\text{A}$		0				
	LOW love love to the set	$V_{CC} = 2.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0	0.2		0.2	1 !
V_{OL}	LOW level output voltage; all outputs	V_{CC} = 2.7 V; V_I = V_{IH} or V_{IL} , I_O = 100 μA		0	0.2		0.2	V
		$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0	0.2		0.2	
		V_{CC} = 4.5 V; V_I = V_{IH} or V_{IL} ; I_O = 100 μA		0	0.2		0.2	
V _{OL}	LOW level output voltage;	$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 6 \text{ mA}$		0.25	0.40		0.50	V
VOL	STANDARD outputs	$V_{CC} = 4.5 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 12 \text{ mA}$		0.35	0.55		0.65] `
I _{OZ}	HIGH level output leakage current	$V_{CC} = 2.0 \text{ V to } 3.6 \text{ V; } V_{I} = V_{IL;}$ $V_{O} = V_{CC} \text{ or GND}$			5.0		10	μА
I _{OZ}	HIGH level output leakage current	$V_{CC} = 2.0 \text{ V to } 3.6 \text{ V; } V_I = V_{IL;}$ $V_O = 6.0 \text{ V}^2$			10		20	μА
I _I	Input leakage current	$V_{CC} = 5.5 \text{ V}; V_I = V_{CC} \text{ or GND}$			1.0		1.0	μА
I _{CC}	Quiescent supply current; SSI	$V_{CC} = 5.5 \text{ V}; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		40	μΑ
Δl _{CC}	Additional quiescent supply current per input	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}; V_{I} = V_{CC} - 0.6 \text{ V}$			500		850	μА

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NOTES:

¹ All typical values are measured at T_{amb} = 25 °C. 2 The maximum operating output voltage (V_{O(max)}) is 6.0 V.

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AC CHARACTERISTICS FOR 74LV03

GND = 0 V; t_r = t_f \leq 2.5 ns; C_L = 50 pF; R_L = 1 $k\Omega$

SYMBOL	PARAMETER	WAVEFORM	/AVEFORM CONDITION		LIMITS −40 to +85 °C			LIMITS -40 to +125 °C	
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX	
t _{PZL} /t _{PLZ} Propagation delay nA, nB, to nY		1.2	-	50	_	_	-		
		Propagation delay nA, nB, to nY Figures, 1, 2	2.0	-	17	26	-	31	
	Propagation delay nA. nB. to nY		2.7	-	13	19	-	23	ns
	,,		3.0 to 3.6	_	10 ²	16	-	19	
			4.5 to 5.5	_	_3	13	_	16	

NOTE:

- 1 Unless otherwise stated, all typical values are at T_{amb} = 25 °C.
- 2 Typical value measured at $V_{CC} = 3.3 \text{ V}$.
- 3 Typical value measured at $V_{CC} = 5.0 \text{ V}$.

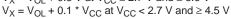
AC WAVEFORMS

 $V_M = 1.5 \text{ V at } V_{CC} \ge 2.7 \text{ V} \le 3.6 \text{ V}$

 $V_M = 0.5 \text{ V} * V_{CC} \text{ at } V_{CC} < 2.7 \text{ V} \text{ and } \ge 4.5 \text{ V}$

 $V_{\mbox{\scriptsize OL}}$ and $V_{\mbox{\scriptsize OH}}$ are the typical output voltage drop that occur with the

 $V_X = V_{OL} + 0.3 \text{ V}$ at $V_{CC} \ge 2.7 \text{ V}$ and $\le 3.6 \text{ V}$



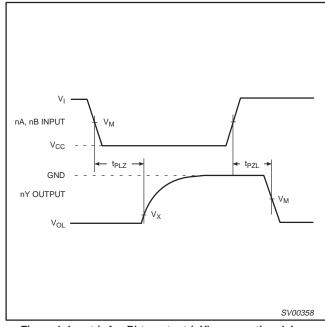


Figure 1. Input (nA, nB) to output (nY) propagation delays.

TEST CIRCUIT

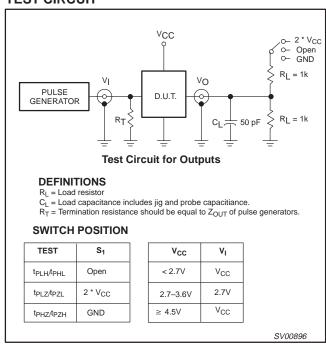


Figure 2. Load circuitry for switching times

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REVISION HISTORY

Rev	Date	Description			
_3	20030303	Product data (9397 750 11191). ECN 853-1963 29494 of 07 February 2003. Supersedes data of 1998 Apr 20 (9397 750 04403).			
		Modifications:			
		Delete DIL, SSOP and TSSOP package ordering and package outlines (discontinued options).			
		Correct power dissipation formula.			
_2	19980420	Product specification (9397 750 04403). ECN 853-1963 19257 of 20 April 1998. Supersedes data of 1997 Mar 28.			

Data sheet status

Level	Data sheet status [1]	Product status ^[2] [3]	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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^[1] Please consult the most recently issued data sheet before initiating or completing a design.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 03-03

Document order number: 9397 750 11191

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^[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.